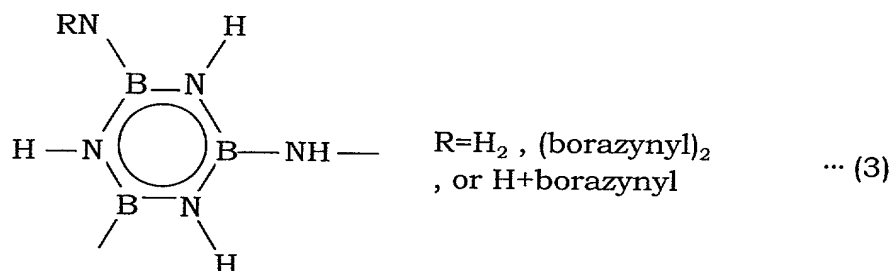
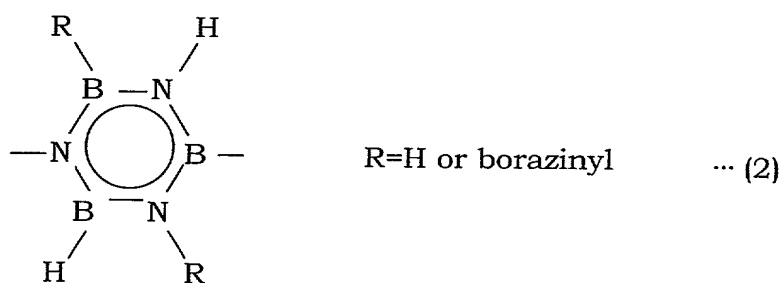
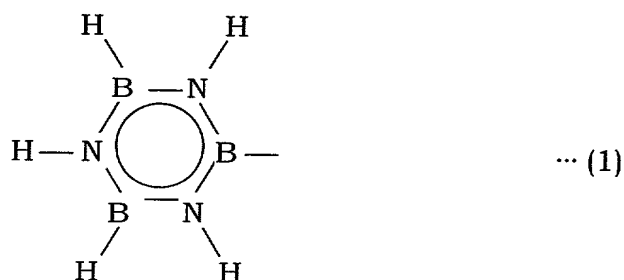


# WHAT IS CLAIMED IS

1. A low dielectric constant material having thermal resistance, comprising borazine skeletal molecules shown by the following formula (1), (2), or (3) in an inorganic or organic material molecule.



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2. An insulation film between semiconductor layers, comprising the low dielectric constant material having thermal resistance of Claim 1.

3. A semiconductor device, comprising an insulation film between semiconductor layers comprising the low dielectric constant material having thermal resistance of Claim 1.